



General Description

The WSK200N08A is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSK200N08A meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

BV _{DSS}	R _{DSON}	I _D
80V	3mΩ	200A

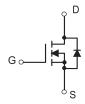
Applications

High power DC/DC converters and switch mode power supply

DC Motor control and Class D Amplifier

TO-263 Pin Configuration





Absolute Maximum Ratings

Symbol	Symbol Parameter		Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	±25	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	200	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	144	А
I _{DM}	Pulsed Drain Current ^{2,} T _C =25°C	790	A
EAS	Avalanche Energy, Single pulse,L=0.5mH	1496	mJ
I _{AS}	Avalanche Current, Single pulse,L=0.5mH	200	А
P _D @T _C =25℃	Total Power Dissipation⁴	345	W
P _D @T _C =100℃	Total Power Dissipation⁴	173	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	175	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		62.5	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		0.43	°C/W



Electrical Characteristics (T_J=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃ , I _D =1mA		0.096		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V,I _D =100A		3.0	4.0	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} . In =250uA	2.0	3.0	4.0	٧
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID -250UA		-5.5		mV/℃
	Drain Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	- uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =80V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			10	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 25V$, V_{DS} = $0V$			±100	nA
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω
Qg	Total Gate Charge (10V)			197		
Q _{gs}	Gate-Source Charge	V_{DS} =80V , V_{GS} =10V , I_D =30A		31		nC
Q _{gd}	Gate-Drain Charge			75		
T _{d(on)}	Turn-On Delay Time			28		
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		18		
T _{d(off)}	Turn-Off Delay Time	$R_G=3\Omega$, $I_D=30A$		42		ns
T _f	Fall Time			54		
C _{iss}	Input Capacitance			8154		
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		1029		pF
C _{rss}	Reverse Transfer Capacitance			650		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =28A	160			mJ

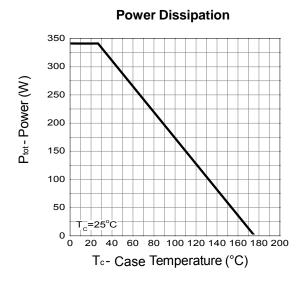
Diode Characteristics

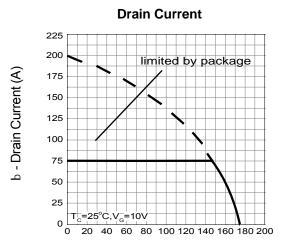
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V =V =0V Force Current			200	Α
I _{SM}	Pulsed Source Current ^{2,6}	V _G =V _D =0V , Force Current			350	Α
V_{SD}	Diode Forward Voltage ² V _{GS} =0V , I _S =15A , T _J =25℃				1.2	V
t _{rr}	Reverse Recovery Time	I= 450 dI/dt 4000 / T 05°C		30		nS
Qrr	Reverse Recovery Charge	IF=15A,dI/dt=100A/µs,T _J =25℃		52		nC

Note * : Pulse test ; pulse width \leq 300 μ s, duty cycle \leq 2%.



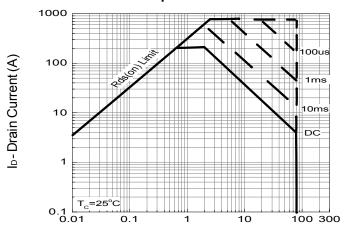
Typical Operating Characteristics





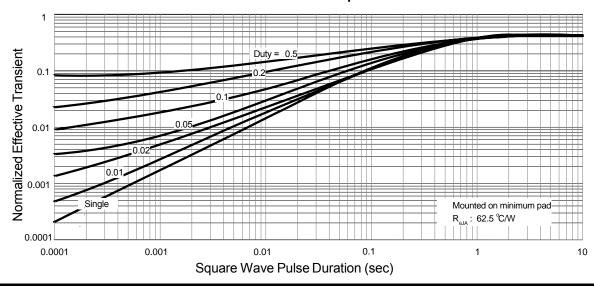
T_c-Case Temperature (°C)

Safe Operation Area



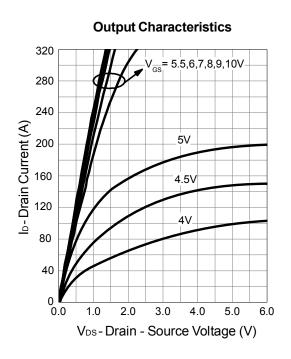
V_{DS} - Drain - Source Voltage (V)

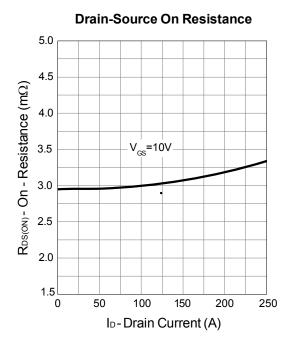
Thermal Transient Impedance

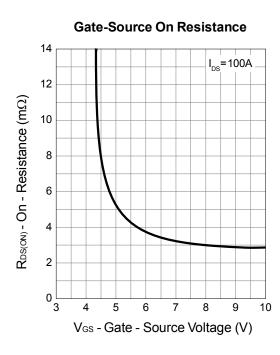


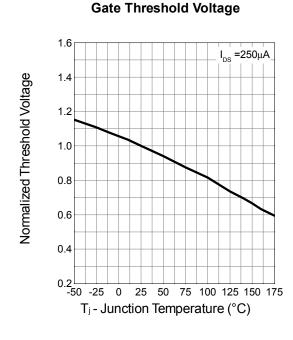


Typical Operating Characteristics (Cont.)











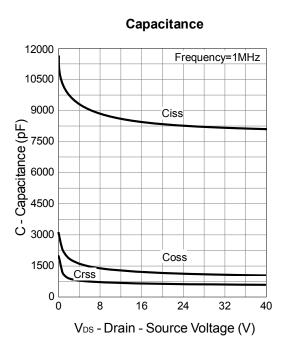
Typical Operating Characteristics (Cont.)

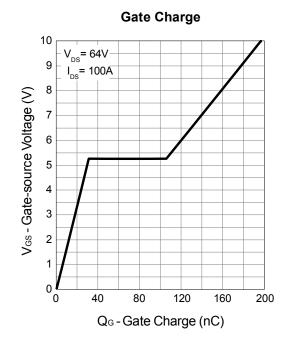
Drain-Source On Resistance = 10V 2.2 = 100A 2.0 Normalized On Resistance 1.8 1.6 1.4 1.2 1.0 0.8 0.6 0.4 $R_{ON} @ T_j = 25^{\circ}C: 2.9m\Omega$ 25 50 75 100 125 150 175

T_j- Junction Temperature (°C)

200 100 T=175°C T=25°C 0.1 0.0 0.2 0.4 0.6 0.8 1.0 1.2 1.4 Vsp - Source - Drain Voltage (V)

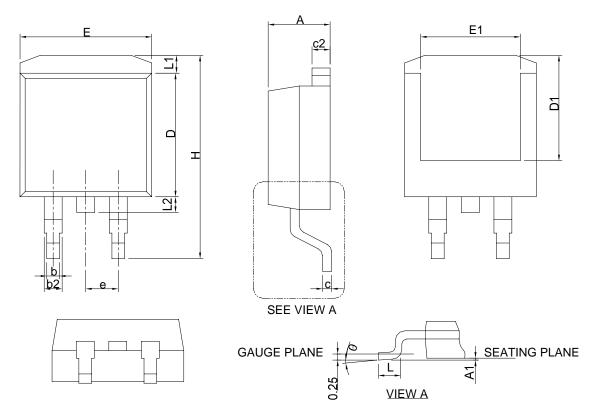
Source-Drain Diode Forward





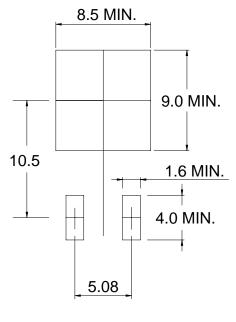


TO-263



Ş	TO-263				
SYMBO	MILLIM	ETERS	INC	HES	
P	MIN.	MAX.	MIN.	MAX.	
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.25	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b2	1.14	1.78	0.045	0.070	
С	0.38	0.74	0.015	0.029	
c2	1.14	1.65	0.045	0.065	
D	8.38	9.65	0.330	0.380	
D1	6.00	9.00	0.236	0.354	
Е	9.65	11.43	0.380	0.450	
E1	6.22	9.00	0.245	0.354	
е	2.54 BSC		0.10	0 BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.68	-	0.066	
L2	-	1.78	-	0.070	
θ	0°	8°	0°	8°	

RECOMMENDED LAND PATTERN



UNIT: mm



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